

1. A lead-free solder consisting essentially of:  
at least one selected from 0.01 0.2% by weight of Mn and 0.01 to 0.2% of Cr;  
at least one selected from 0.5 to 9% by weight of Ag and 0.5 to 5% by weight of Sb; and  
90.5% by weight or more of Sn.
2. A lead-free solder according to claim 1 consisting essentially of:  
at least one selected from 0.05 to 0.1% by weight of Mn and 0.05 to 0.1% by weight of Cr;  
at least one selected from 3 to 5% by weight of Ag and 0.5 to 5% by weight of Sb; and  
90.5% by weight or more of Sn.
3. A lead-free solder according to claim 2 containing only one member of each of said groups.
4. A lead-free solder according to claim 3 wherein the member of the group of Ag and Sb is Sb.
5. A soldered article comprising an article containing a transition metal conductor and being joined through a solder, said transition metal conductor being liable to spread in molten Sn, wherein said solder is a lead free solder according to claim 1.

6. A soldered article according to claim 5, wherein said transition metal conductor comprises at least one selected from elementary substances or alloys thereof of the group consisting of Cu, Ag, Ni, Au, Pd, Pt and Zn.

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